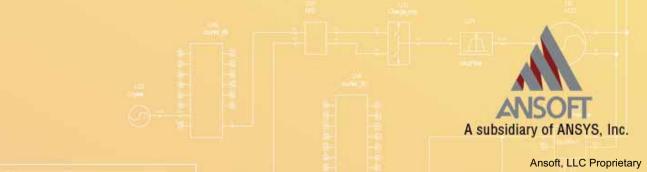


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EMI Driven by PI



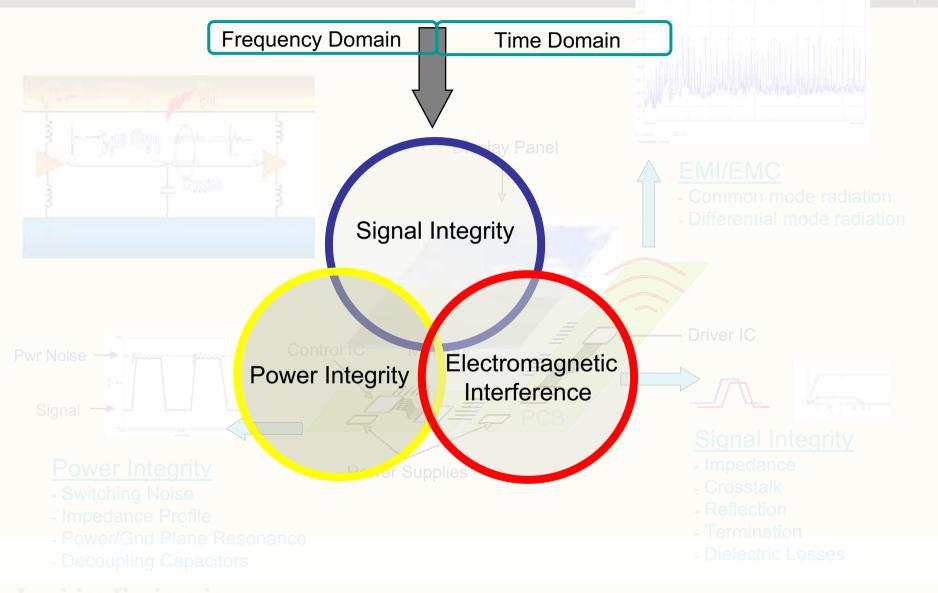
<u>Outline</u>



- SI + PI = EMI
 - These disciplines are no longer independent of each other
- Fundamentals of EMI
 - Where does it come from and how is it minimized
 - Five Step EMC Design Flow
- Power Integrity design methodology to reduce EMI
 - Fundamentals of Power Integrity
 - Design Process to meet design specs in the Time and Frequency domain
- 2nd Presentation on EMI Driven by SI
 - Fundamentals of Signal Integrity
 - Crosstalk is the main contributor to EMI
 - Case studies that show perils of crosstalk in real world designs

SI/PI/EMI Design Overview

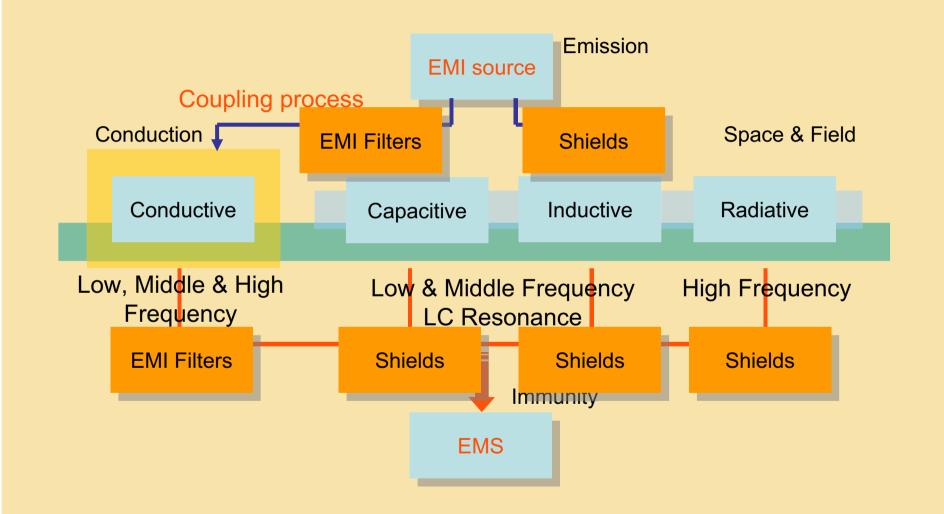




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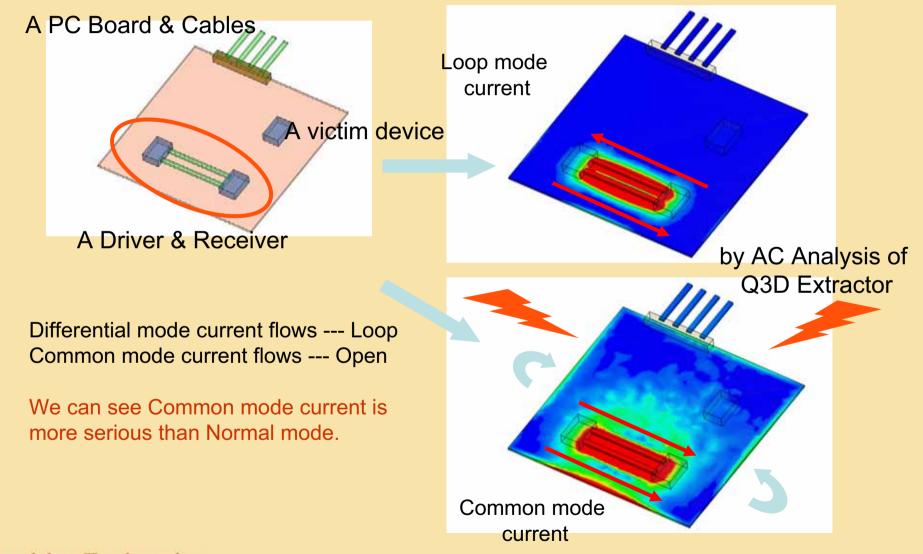
Three Basic Elements of EMC





Loop Mode & Common Mode Noise

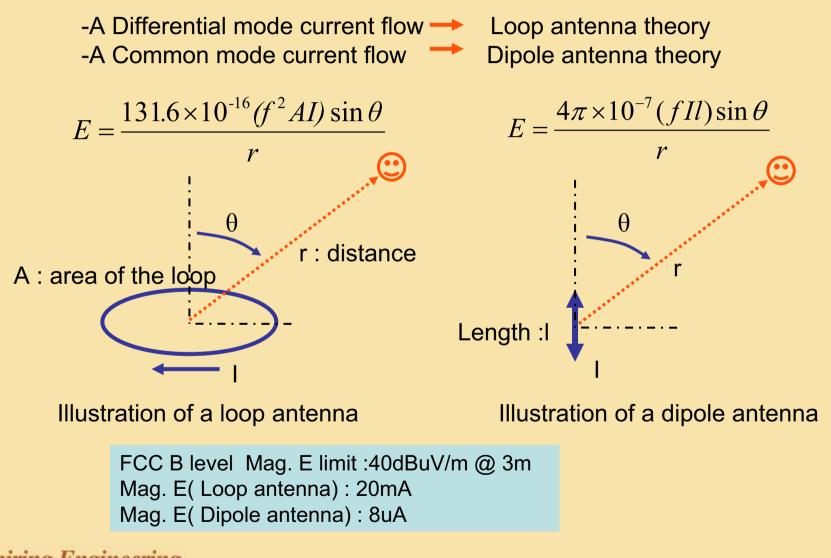




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Antenna theory





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Impedance Analysis

Resonance Analysis

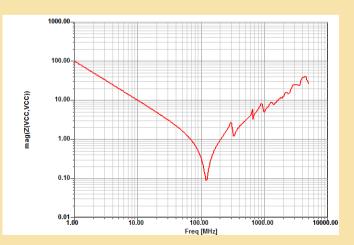
Planes deliver power to ICs and return path for signal

Ensure that Plane impedance is smooth and low over broad frequency range

Signal Extraction

Emissions Analysis

Enclosure Simulation



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Impedance Analysis

Resonance Analysis

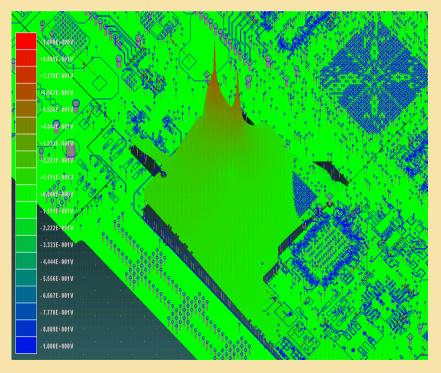
Signal Extraction

Emissions Analysis

Enclosure Simulation

Resonances indicate areas of high impedance and EMI potential

Ensure power planes do not resonant in critical locations



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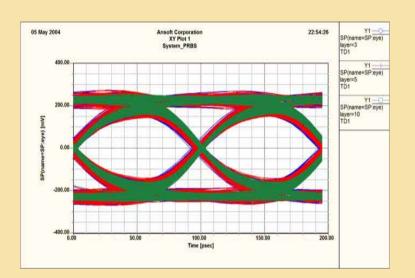
Impedance Analysis

Resonance Analysis

Signal Extraction

Emissions Analysis

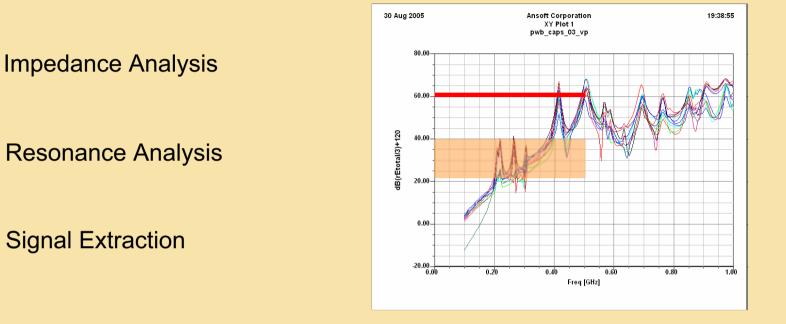
Enclosure Simulation



If signal is not at the receiver, it went somewhere else

Ensure clean signal transmission and good return path for critical nets





Emissions Analysis

Non-ideal planes and tight routing can lead to unintentional signals

Enclosure Simulation

Ensure there are no unintentional radiators



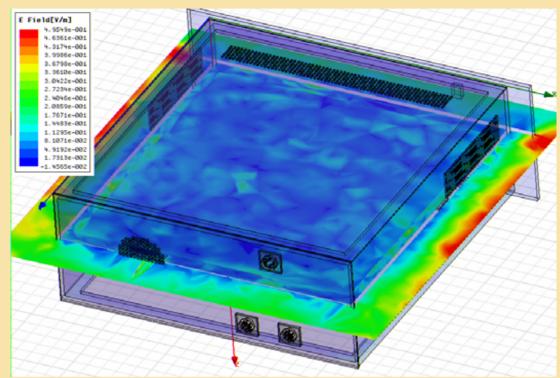
Impedance Analysis

Resonance Analysis

Signal Extraction

Emissions Analysis

Enclosure Simulation



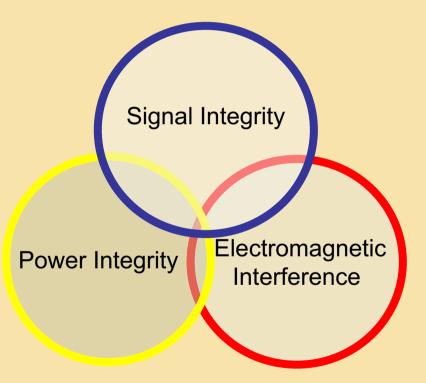
Real enclosures are non-ideal and can pass radiation

Ensure minimal radiation from PCB escapes the chassis holes

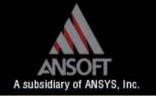
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PI Methodology





Power Integrity – A Case Study



- Active devices require clean power to operate correctly
- Power distribution system (PDS) design engineers must ensure that all parts receive voltage between certain limits and that noise is kept sufficiently low
- Today's designs with many separate power domains of high current and low voltage devices complicate power integrity analysis

Board Imported from Layout



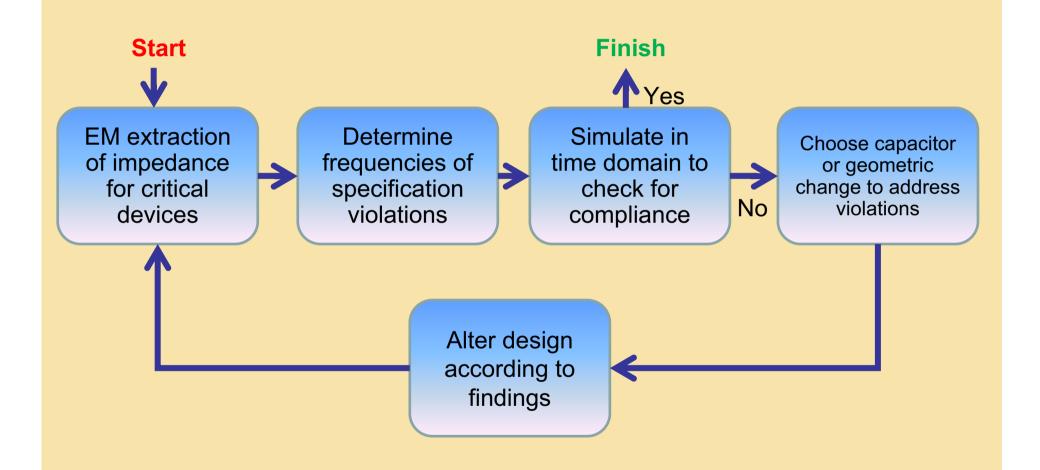
VRM 0000000000 0000008 eleccoccocce

Measuring impedance at the six VCC pins on U41

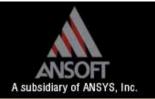
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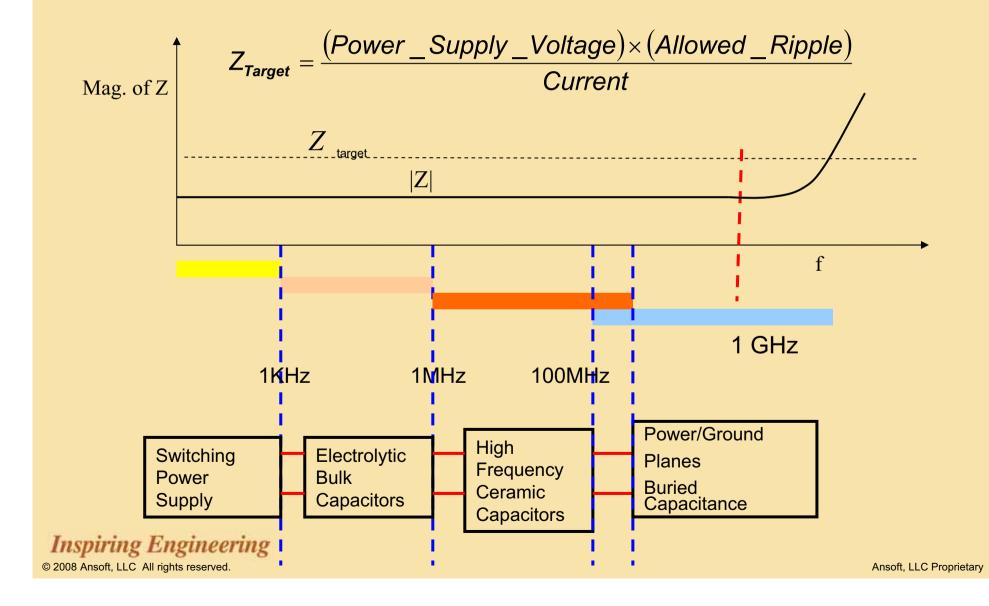
PDS Design Flow





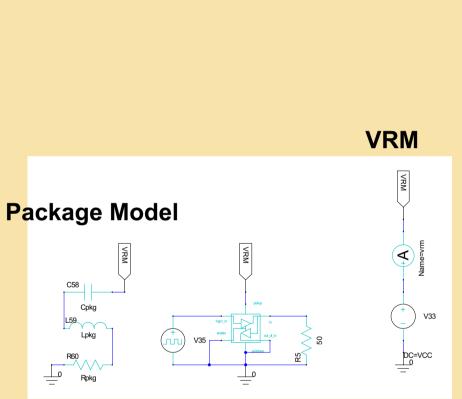
Frequency Domain PDS Targets





Defining the Target Impedance





Driver

- To define the target impedance we need to consider two factors:
 - Peak current
 - Determines maximum impedance
 - Spectral power
 - Determines cutoff frequency

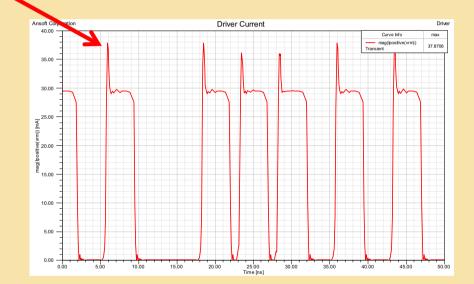
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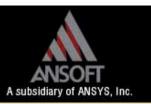
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Peak Current

- Peak driver current 37.87 mA
- Example:
 - Six drivers and 0.18 V maximum voltage swing:

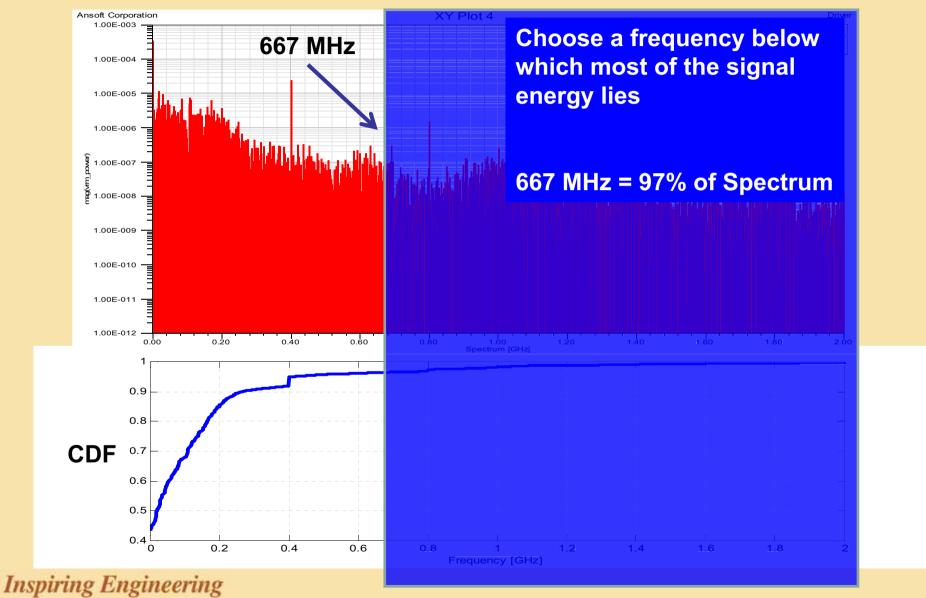
$$\frac{0.18\,\mathrm{V}}{6(37.87\,\mathrm{mA})} = 800\,\mathrm{m}\Omega$$





Driver Spectrum



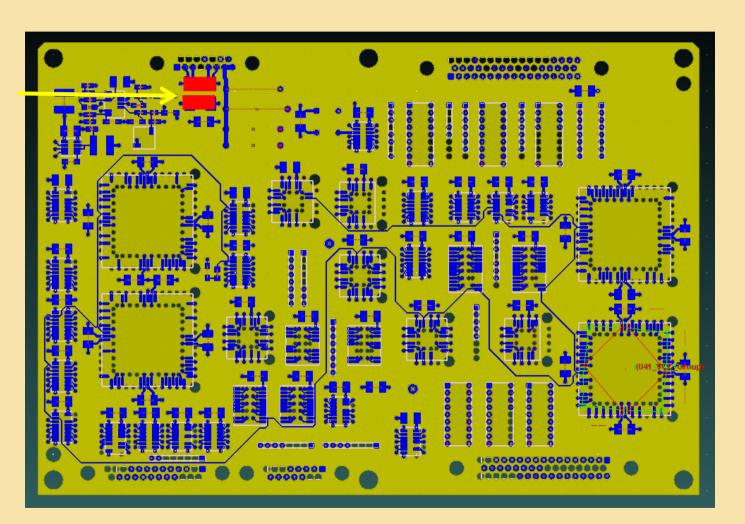


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Power Integrity Investigation

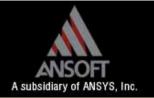


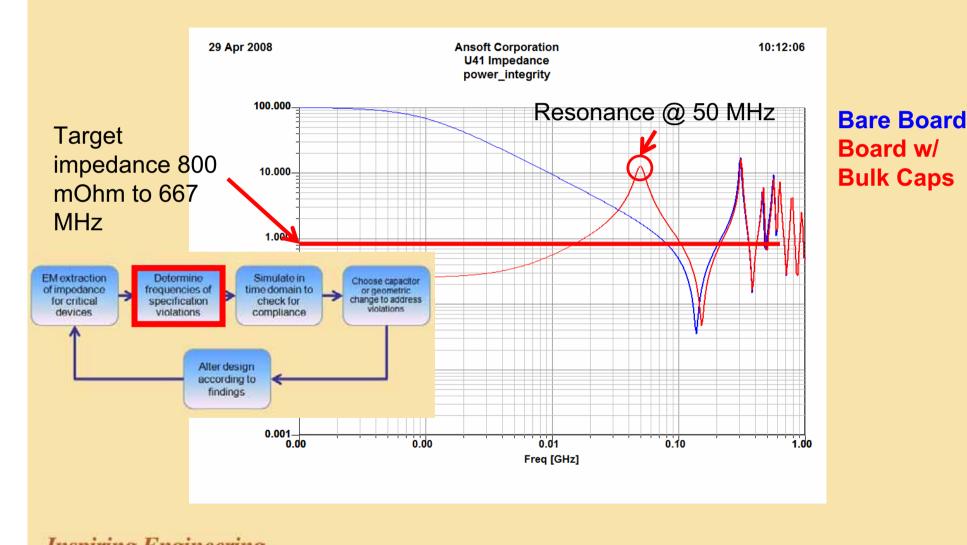
Added two bulk 47 uF capacitors as specified by VRM manufacturer



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Bare Board vs. Bulk Capacitors

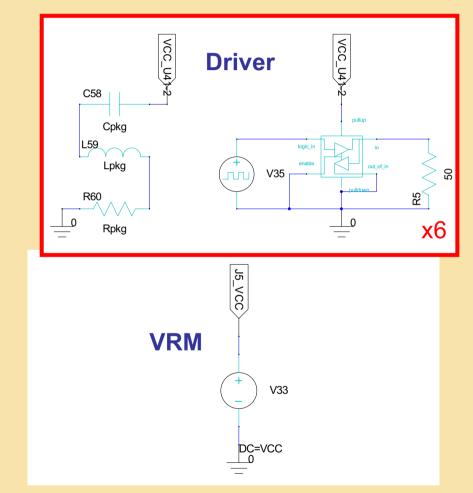


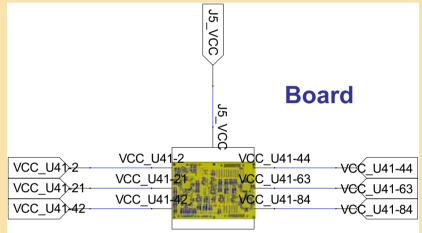


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Time Domain Schematic







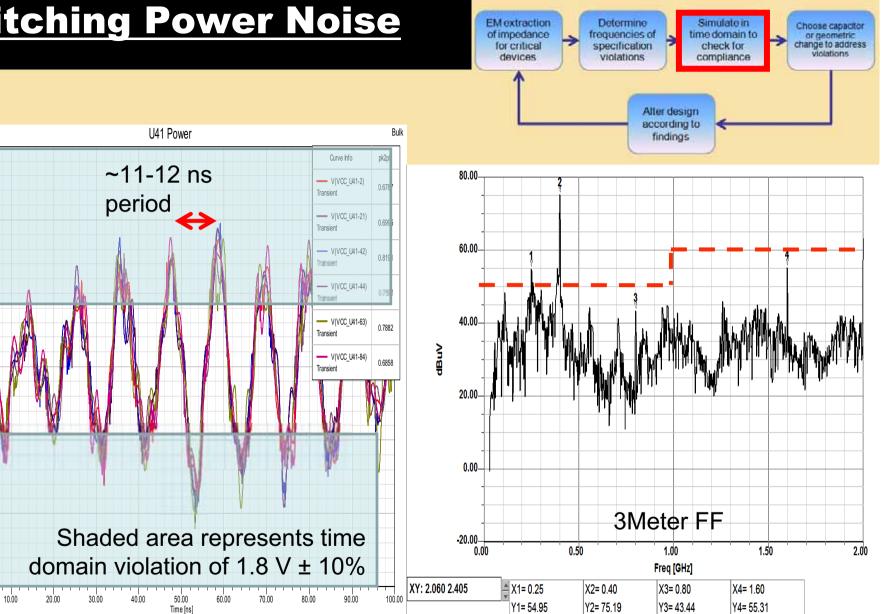
800 Mbps data rate

DDR2 IBIS driver into ideal termination used as load for PDS

Package decoupling modeled using a capacitor w/ ESR, ESL

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Switching Power Noise



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Ansoft Corporation

2.40

2.20 -

2.00

Y 1 [V]

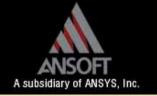
1.60

1.40

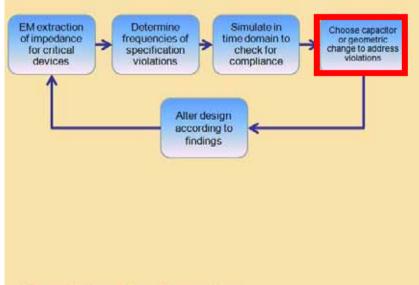
1.20 -

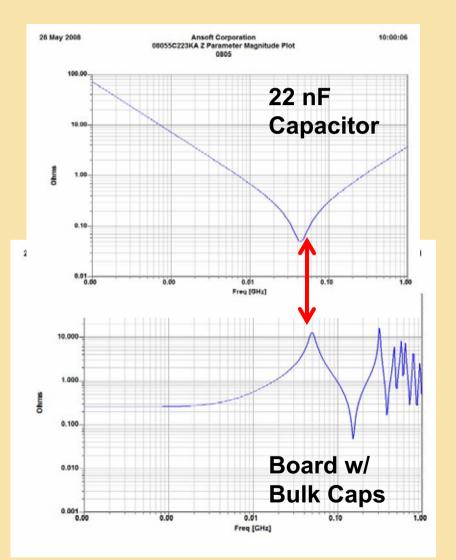
0.00

Choosing a Decoupling Capacitor



 To reduce the effect of a resonance, choose a capacitor with a low impedance at the resonant frequency

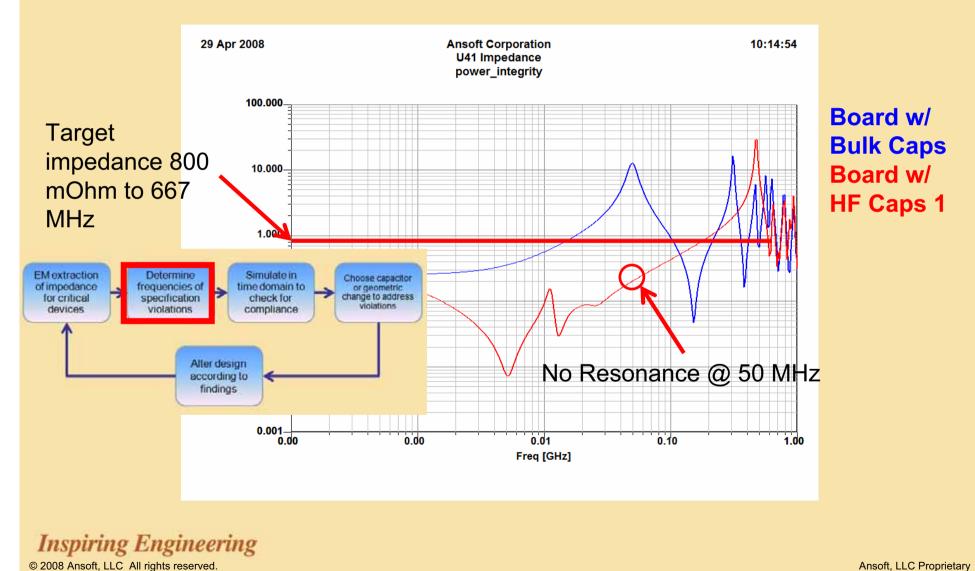


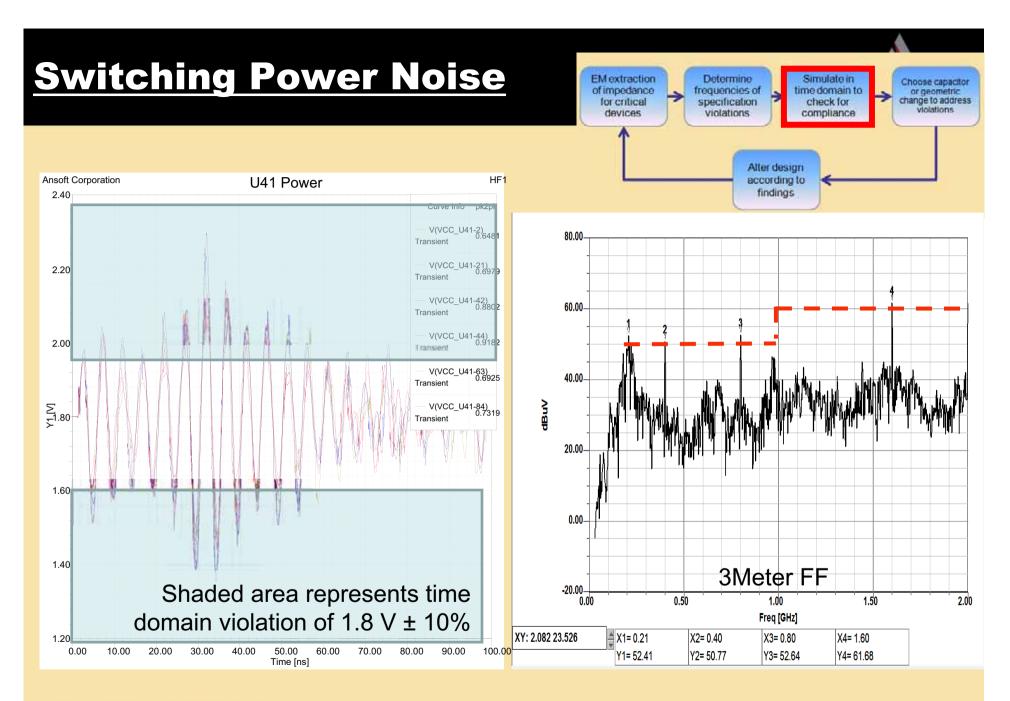


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Bulk vs. HF Capacitors 1





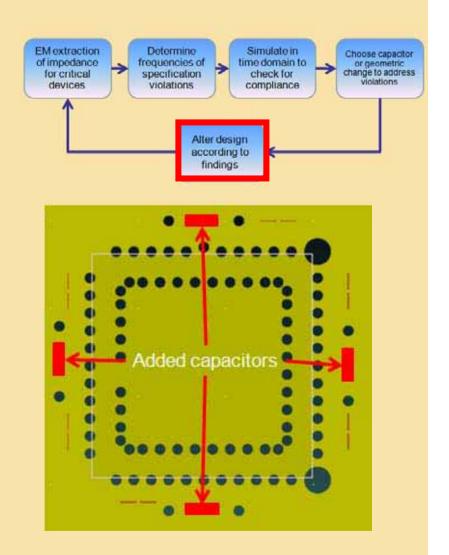


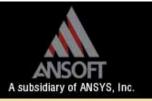
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Extending Low Impedance

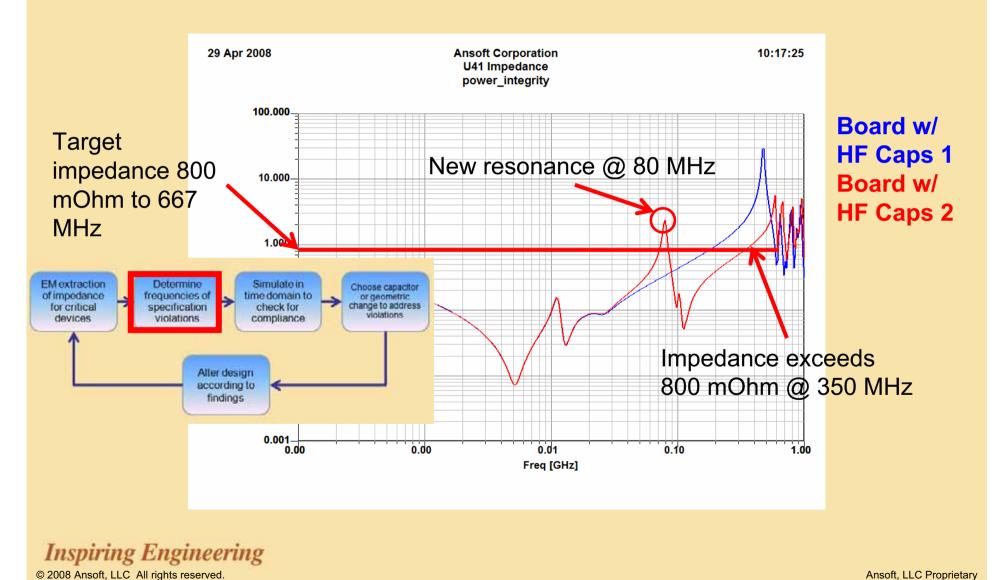
- 10 1.2 nF capacitors were added across the board to extend minimum high-frequency impedance
- 1.2 nF capacitor was chosen due to low impedance at 200 MHz
- 4 of these were located near U41

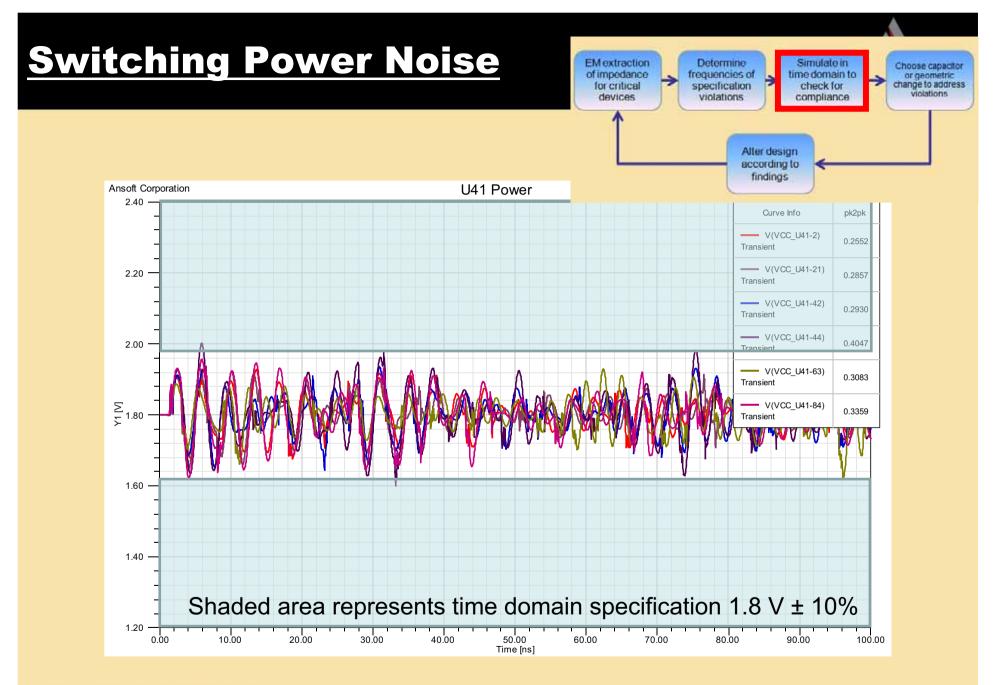




HF 1 vs. HF 2



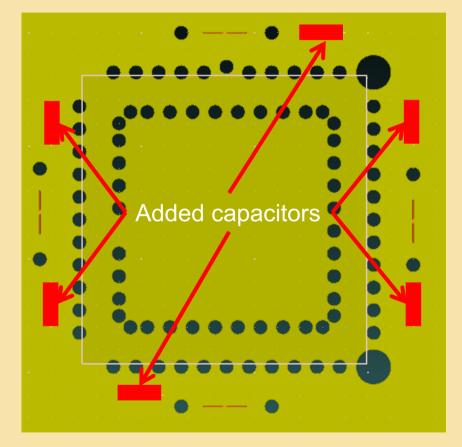




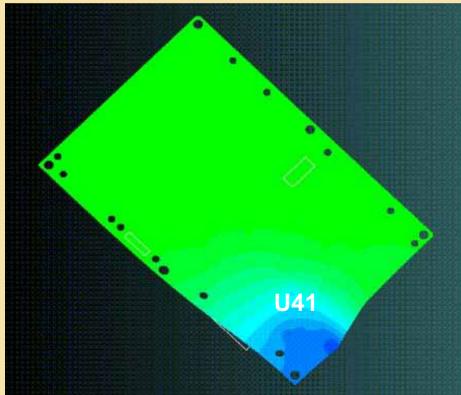
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Removing a Resonance



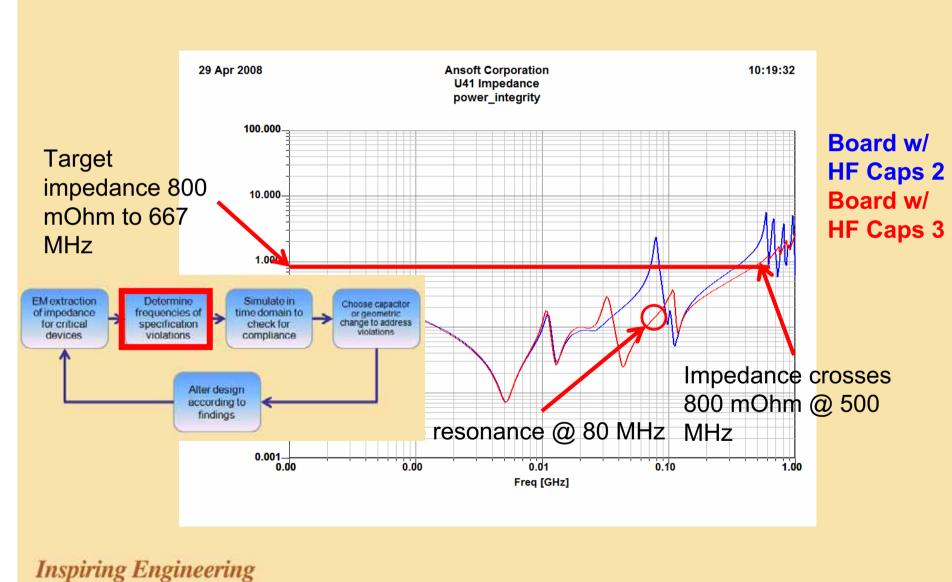


 Six 8 nF capacitors were added near U41 to cancel resonance at 80 MHz



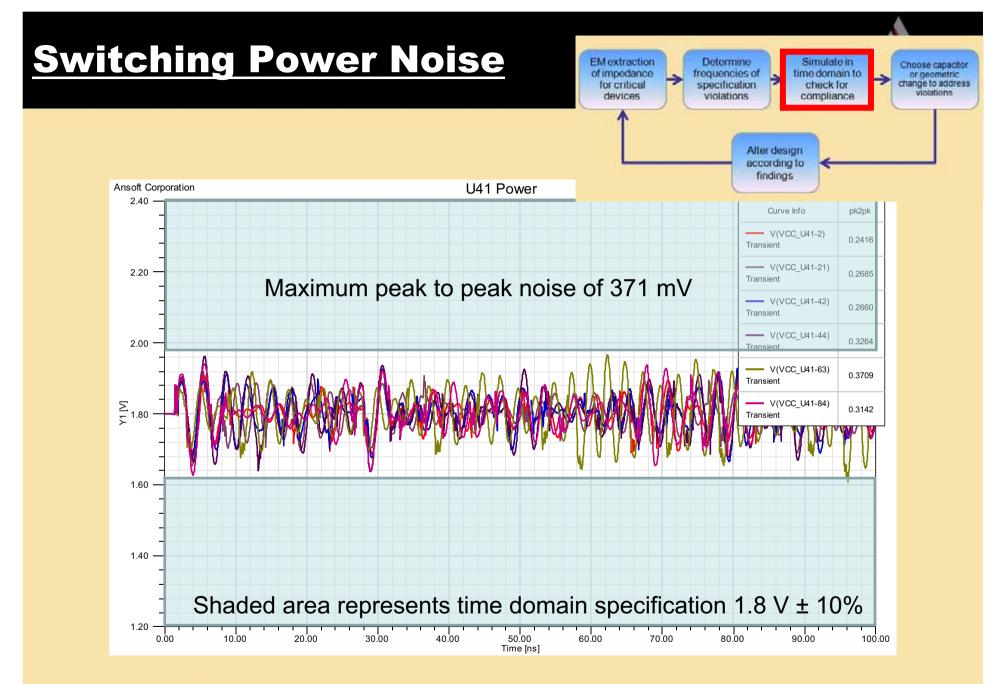
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<u>HF 2 vs. HF 3</u>





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Buried Capacitance

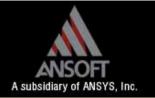


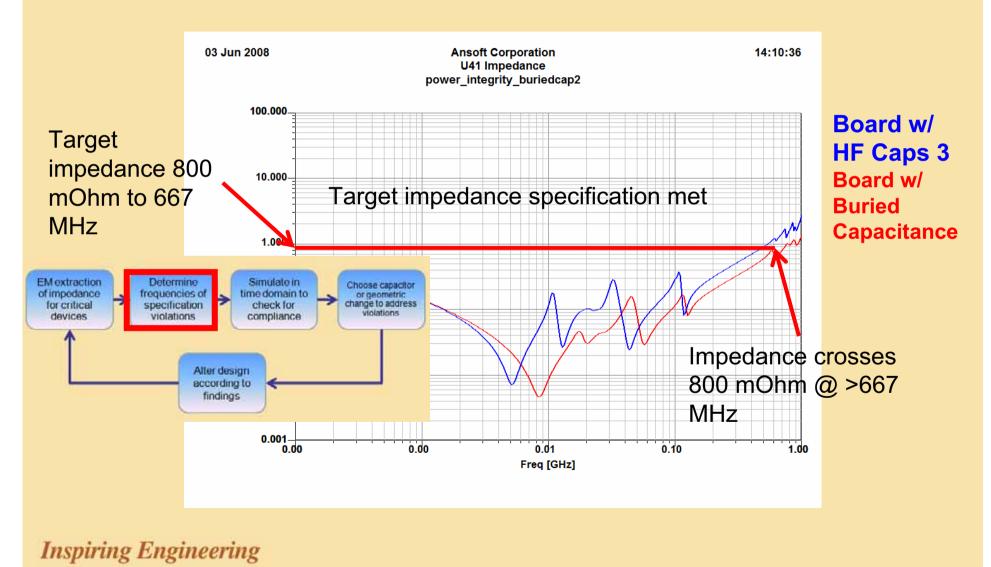
- Due to parasitic inductance it is impossible to decouple the board with capacitors at frequencies greater than a few hundred MHz
- Using a thinner dielectric layer between power and ground planes introduces additional capacitance and reduces high frequency impedance

Capacitance of parallel plates:
$$C = \varepsilon \frac{A}{d}$$

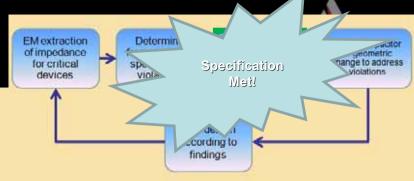
HF 3 vs. Buried Capacitance

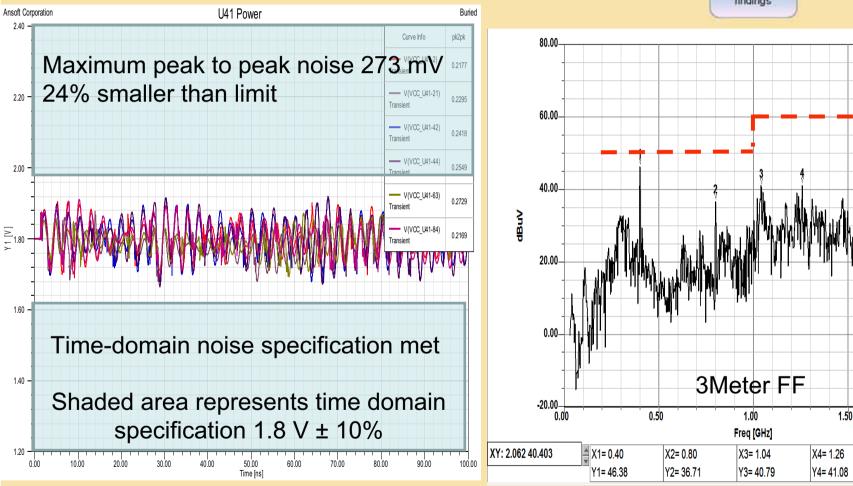
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Switching Power Noise





X5= 1.60

Y5= 53.75

2.00

<u>Conclusions</u>



- SI / PI / EMI are all based on the same electromagnetic fundamentals and cannot be separated
- Impedance and resonant mode simulations connect the frequency domain to the spatial domain and allow selection of capacitor value and placement
- Frequency domain extractions are useful for quickly optimizing PDS designs, but *time domain* simulations are necessary to ensure compliance with device specs
- Using a single design environment can help reuse the same models for SI/PI/EMI simulations





Any Questions?

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